

## PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT																
NATURE OF CONVEYANCE:	ASSIGNMENT																
<b>CONVEYING PARTY DATA</b>																	
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Xin-Hua Huang</td> <td>01/18/2012</td> </tr> <tr> <td>Ping-Yin Liu</td> <td>01/18/2012</td> </tr> <tr> <td>Li-Cheng Chu</td> <td>01/18/2012</td> </tr> <tr> <td>Yuan-Chih Hsieh</td> <td>01/18/2012</td> </tr> <tr> <td>Lan-Lin Chao</td> <td>01/18/2012</td> </tr> <tr> <td>Chun-Wen Cheng</td> <td>01/18/2012</td> </tr> <tr> <td>Chia-Shiung Tsai</td> <td>01/18/2012</td> </tr> </tbody> </table>		Name	Execution Date	Xin-Hua Huang	01/18/2012	Ping-Yin Liu	01/18/2012	Li-Cheng Chu	01/18/2012	Yuan-Chih Hsieh	01/18/2012	Lan-Lin Chao	01/18/2012	Chun-Wen Cheng	01/18/2012	Chia-Shiung Tsai	01/18/2012
Name	Execution Date																
Xin-Hua Huang	01/18/2012																
Ping-Yin Liu	01/18/2012																
Li-Cheng Chu	01/18/2012																
Yuan-Chih Hsieh	01/18/2012																
Lan-Lin Chao	01/18/2012																
Chun-Wen Cheng	01/18/2012																
Chia-Shiung Tsai	01/18/2012																
<b>RECEIVING PARTY DATA</b>																	
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.																
Street Address:	No. 8, Li-Hsin Rd. 6																
Internal Address:	Science-Based Industrial Park																
City:	Hsin-Chu																
State/Country:	TAIWAN																
Postal Code:	300-77 R.O.C.																
<b>PROPERTY NUMBERS Total: 1</b>																	
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13365043</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13365043												
Property Type	Number																
Application Number:	13365043																
<b>CORRESPONDENCE DATA</b>																	
Fax Number:	(972)732-9218																
Phone:	972-732-1001																
Email:	docketing@slater-matsil.com																
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>																	
Correspondent Name:	Slater & Matsil, L.L.P.																
Address Line 1:	17950 Preston Road																
Address Line 2:	Suite 1000																
Address Line 4:	Dallas, TEXAS 75252																

CH \$40.00 13365043

PATENT

ATTORNEY DOCKET NUMBER:	TSM11-1033
NAME OF SUBMITTER:	Kasey Edwards
Total Attachments: 2 source=TSM11-1033_Assignment#page1.tif source=TSM11-1033_Assignment#page2.tif	

ATTORNEY DOCKET NO.  
TSM11-1033

**ASSIGNMENT**

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on the date set forth below; and

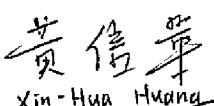
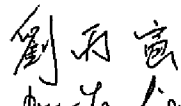

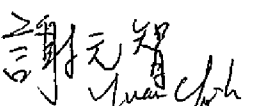
WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. (TSMC), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C., is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said TSMC, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said TSMC, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to TSMC, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said TSMC, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TSMC, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	<i>Methods of Bonding Caps for MEMS Devices</i>			
SIGNATURE OF INVENTOR AND NAME	 Xin-Hua Huang Xin-Hua Huang	 Ping-Yin Liu	 Li-Cheng Chu	 Yuan-Chih Hsieh
DATE	01/18/2012	01.18.2012	01.18.2012	01.18.2012
RESIDENCE (City, County, State)	Xihu Township, Taiwan	Yonghe City, Taiwan	Taipei City, Taiwan	Hsin-Chu, Taiwan

ATTORNEY DOCKET NO.  
TSM11-1033

**ASSIGNMENT**

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on the date set forth below; and

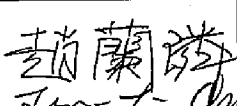
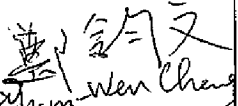
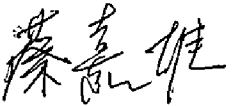
WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. (TSMC), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C., is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said TSMC, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said TSMC, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to TSMC, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said TSMC, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TSMC, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	<b>Methods of Bonding Caps for MEMS Devices</b>			
SIGNATURE OF INVENTOR AND NAME	 Lan-Lin Chao	 Chun-Wen Cheng	 Chia-Shiung Tsai	
DATE	01/18/2012	01/18/2012	01/18/2012	
RESIDENCE (City, County, State)	Sindian City, Taiwan	Zhubei City, Taiwan	Hsin-Chu, Taiwan	